

REMARKS

Claims 11, 13, 15, 17, 19-21, 23, 25, 26, and 28 are in the application, with Claims 11, 13, 15, 17, 21, 23, 26, and 28 having been amended. Claims 11, 15, 21, and 26 are the independent claims herein. No new matter has been added. Reconsideration and further examination are respectfully requested.

Claims 11, 13, 15, 17, 19-21, and 23 stand rejected under 35 U.S.C. §102 as being allegedly anticipated by U.S. Patent No. 6,010,342 (“Watson”). Claims 21 and 25 are rejected under 35 U.S.C. §102 as being allegedly anticipated by U.S. Patent No. 3,963,316 (“Williams”). Claim 26 and 28 stand rejected under 35 U.S.C. §103 as being unpatentable over Williams in view of U.S. Patent No. 6,898,085 (“Haba”). Reconsideration and withdrawal of the rejections are respectfully requested.

Claims 11 and 15

Amended independent claim 11 recites an electronic component body and one or more leads coupled to the electronic component body. One lead includes a first leg and a second leg. The second leg includes a first portion defining a first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion that is substantially parallel to the first leg. The third portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate, and defines a vertex of the first obtuse angle that is to abut the substrate. The substrate is to be disposed between the vertex and the electronic component body.

FIG. 2 of the present application reflects one embodiment of the foregoing features. Attachment A is a marked-up version of FIG. 2 showing lead 35 including first leg 36 and second leg 37, which define first acute angle 38 therebetween. Second leg 37 includes first portion X defining first acute angle 38 with first leg 36, second portion Y defining second acute angle 38A with first portion X, and third portion Z defining first obtuse angle 38B with the second portion Y, wherein the third portion Z is substantially parallel to first leg 36. As shown, vertex V of the first obtuse angle is to abut substrate 40, and substrate 40 is to be disposed between vertex V and electronic component body 20. Also, as shown, third portion Z that is substantially parallel to first leg 36 is substantially equal to a thickness of substrate 40. In some embodiments, such

features provide the ability to mount an electronic component body to a substrate using a single lead.

The art of record is not seen to disclose or to suggest the above features of amended independent claim 11. In particular, the art of record is not seen to disclose or suggest a third portion defining a first obtuse angle with a second portion, wherein a length of the third portion is substantially parallel to a first leg and is substantially equal to a thickness of a substrate, wherein a vertex of the first obtuse angle is to abut the substrate, and wherein the substrate is to be disposed between the vertex and an electronic component body.

Watson relates to a compression connector for interconnecting microelectronic circuit and cable assemblies. Elements 95A and 95B of Watson are parallel to one another and may be equal in length to a thickness of housing 25. However, neither one of elements 95A and 95B can remotely be seen to disclose or suggest a third portion defining a first obtuse angle with a second portion, wherein a length of the third portion is substantially parallel to a first leg and is substantially equal to a thickness of a substrate, wherein a vertex of the first obtuse angle is to abut the substrate, and wherein the substrate is to be disposed between the vertex and an electronic component body. In fact, nowhere does Watson disclose or suggest a substrate disposed between a vertex of an obtuse angle and an electronic component body.

The remaining art of record has been reviewed and is not seen to remedy the foregoing deficiencies in Watson. Therefore, the art of record, taken alone or in any permissible combination, is not seen to disclose or suggest a lead with a third portion defining a first obtuse angle with a second portion, wherein a length of the third portion is substantially parallel to a first leg and is substantially equal to a thickness of a substrate, wherein a vertex of the first obtuse angle is to abut the substrate, and wherein the substrate is to be disposed between the vertex and an electronic component body.

In view of the foregoing, amended independent claim 11 is believed to be in condition for allowance. Claim 13 depends from claim 11 and is therefore also believed to be allowable for at least the foregoing reasons.

Amended independent claim 15 relates to a method in which, among other features, a third portion defines a first obtuse angle with a second portion, where the third portion is substantially parallel to a first leg and is substantially equal to a thickness of a substrate, wherein

a vertex of the first obtuse angle is to abut the substrate, and wherein the substrate is to be disposed between the vertex and the electronic component body. In view of the foregoing, amended independent claim 15 is believed to be in condition for allowance. Claims 17, 19, and 20 depend from claim 15 and are therefore also believed to be allowable for at least the foregoing reasons.

Claim 21

Amended independent claim 21 recites a method of placing a lead of an electronic component body into the body of a substrate. The lead includes a first leg and a second leg. The second leg includes a first portion defining a first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion that is substantially parallel to the first leg. The third portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate, defines a vertex of the first obtuse angle that is to abut the substrate, and wherein the substrate is to be disposed between the vertex and the electronic component body.

The art of record is not seen to disclose or to suggest the above features of amended independent claim 21. In particular the art of record is not seen to disclose or suggest a lead with a third portion defining a first obtuse angle with a second portion, wherein the third portion is substantially parallel to a first leg and is substantially equal to a thickness of the substrate, wherein a vertex of the first obtuse angle is to abut a substrate and wherein the substrate is to be disposed between the vertex and an electronic component body.

As mentioned above, Watson cannot be seen to disclose or suggest a third portion defining a first obtuse angle with a second portion, where the third portion is substantially parallel to a first leg and is substantially equal to a thickness of a substrate, wherein a vertex of the first obtuse angle is to abut the substrate, and wherein the substrate is to be disposed between the vertex and the electronic component body.

Williams relates to an electrical connector inserted into a circuit board. Williams shows sidewall 34 which may be equal in thickness to board 60. Sidewall 34 is not substantially parallel to segment 40, which forms an acute angle with segment 38.

Accordingly, Williams cannot be seen to disclose or suggest a lead with a third portion defining a first obtuse angle with a second portion, wherein a length of the third portion is substantially parallel to a first leg and is substantially equal to a thickness of the substrate, wherein a vertex of the first obtuse angle is to abut a substrate, and wherein the substrate is to be disposed between the vertex and an electronic component body.

In view of the foregoing, amended independent claim 21 is believed to be in condition for allowance. Claim 25 depends from claim 21 and is therefore also believed to be allowable for at least the foregoing reasons.

Claim 26

Independent claim 26 relates to an expansion card comprising a circuit board; a connector coupled to the circuit board, the connector to connect to a motherboard; and an electronic component body coupled to the circuit board, the electronic component body comprising one or more leads coupled to and extending from the electronic component body. One lead includes a first leg and a second leg. The second leg includes a first portion defining a first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion that is substantially parallel to the first leg. A length of the third portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate, and a vertex of the first obtuse angle is to abut the substrate, wherein the substrate is to be disposed between the vertex and the electronic component body.

As discussed above, Williams does not disclose or suggest a lead with a third portion defining a first obtuse angle with a second portion, wherein a length of the third portion is substantially parallel to a first leg and is substantially equal to a thickness of the substrate, wherein a vertex of the first obtuse angle is to abut a substrate, and wherein the substrate is to be disposed between the vertex and an electronic component body.

Haba describes bus systems that are formed by the interconnection of various module structures. Haba has been reviewed and is not seen to provide the missing elements of Williams. In view of the foregoing, amended independent claim 26 is believed to be in condition for allowance. Claim 28 depends from claim 26 and is therefore also believed to be allowable for at least the foregoing reasons.

C O N C L U S I O N

The outstanding Office Action presents a number of characterizations regarding the applied references, some of which are not directly addressed herein because they are not related to the rejections of the independent claims. Applicants do not necessarily agree with the characterizations and reserve the right to further discuss those characterizations.

For at least the reasons given above, it is submitted that the entire application is in condition for allowance and such action is respectfully requested at the Examiner's earliest convenience. Alternatively, if there remains any question regarding the present application or any of the cited references, or if the Examiner has any further suggestions for expediting allowance of the present application, the Examiner is kindly invited to contact the undersigned via telephone at (203) 972-0049.

Respectfully submitted,



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Date

Nandu A. Talwalkar
Registration No. 41,339
Buckley, Maschoff & Talwalkar LLC
Attorneys for INTEL Corporation
Five Elm Street
New Canaan, CT 06840
(203) 972-0049

Attachment: Attachment A